Abstracts

A fully-integrated broadband amplifier MMIC employing a novel chip size package

Young Yun, M. Nishijima, M. Katsuno, H. Ishida, K. Minagawa, T. Nobusada and T. Tanaka. "A fully-integrated broadband amplifier MMIC employing a novel chip size package." 2002 MTT-S International Microwave Symposium Digest 02.1 (2002 Vol. I [MWSYM]): 409-412 vol.1.

In this work, using a novel RF-CSP, a broadband amplifier MMIC including all the matching and biasing components was developed for Ku and K band applications. To integrate DC biasing components on the MMIC, an STO (SrTiO/sub 3/) capacitor was employed. By employing an anisotropic conductive film for the RF-CSP, the MMIC fabrication process became very simple and cost effective. The packaged amplifier MMIC exhibited good RF performance in a wide frequency range. This work is the first report for fully-integrated Ku or K band MMICs which have all the biasing and matching components.

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